



**THE DATASHEET OF  
LQH2MPZ2R2MGRL**



**CHIP COILS (CHIP INDUCTORS) LQH2MPZ□□□□GR□**  
**Murata Standard Reference Specification [AEC-Q200]**

**1. Scope**

This reference specification applies to chip coils (chip inductors) LQH2MPZ\_GR series for automotive electronics based on AEC-Q200 except for power trains and safeties.

**2. Part Numbering**

(Ex.)

LQ	H	2M	P	Z	100	M	G	R	L
Product ID	Structure	Dimension (L × W)	Application and characteristic	Category	Inductance	Tolerance	Dimension (T)	Other	Packaging L: ø180 taping

**3. Part Number and Rating**

Operating temperature range	(ambient temperature not including self-temperature rise)	-40°C to +105°C
	(product temperature including self-temperature rise)	-40°C to +125°C
Storage temperature range		-40°C to +105°C

Customer Part number	Murata Part number	Inductance		DC resistance (Ω)	Self-resonant frequency (MHz min.)	Rated current (mA) <sup>3</sup>			ESD 2: 2 kV
		Nominal value (μH)	Tolerance (%)			Based on inductance change <sup>1</sup>	Based on temperature rise <sup>2</sup>		
							Ambient temperature 85°C	Ambient temperature 105°C	
	LQH2MPZR33NGRL	0.33	N: ±30	0.15±20%	130	2200	1130	670	2
	LQH2MPZR47NGRL	0.47	N: ±30	0.18±20%	120	1950	1060	630	2
	LQH2MPZ1R0NGRL	1.0	N: ±30	0.25±20%	100	1550	900	540	2
	LQH2MPZ1R5NGRL	1.5	N: ±30	0.32±20%	60	1330	790	470	2
	LQH2MPZ2R2MGRL	2.2	M: ±20	0.39±20%	50	1180	680	400	2
	LQH2MPZ3R3MGRL	3.3	M: ±20	0.47±20%	45	1020	640	380	2
	LQH2MPZ4R7MGRL	4.7	M: ±20	0.60±20%	40	870	580	340	2
	LQH2MPZ6R8MGRL	6.8	M: ±20	0.72±20%	35	730	530	310	2
	LQH2MPZ100MGRL	10	M: ±20	0.88±20%	30	610	480	280	2
	LQH2MPZ150MGRL	15	M: ±20	1.7±20%	25	490	340	200	2
	LQH2MPZ220MGRL	22	M: ±20	2.1±20%	20	410	290	170	2
	LQH2MPZ330MGRL	33	M: ±20	4.3±20%	15	310	200	120	2
	LQH2MPZ470MGRL	47	M: ±20	5.3±20%	10	270	180	110	2
	LQH2MPZ680MGRL	68	M: ±20	6.7±20%	7	230	160	100	2
	LQH2MPZ820MGRL	82	M: ±20	7.3±20%	5	210	150	90	2

\*1 When rated current is applied to the products, inductance will be within ±30% of initial inductance value range.

\*2 When rated current is applied to the products, temperature rise caused by self-generated heat shall be limited to 40°C max (ambient temperature 85°C max).

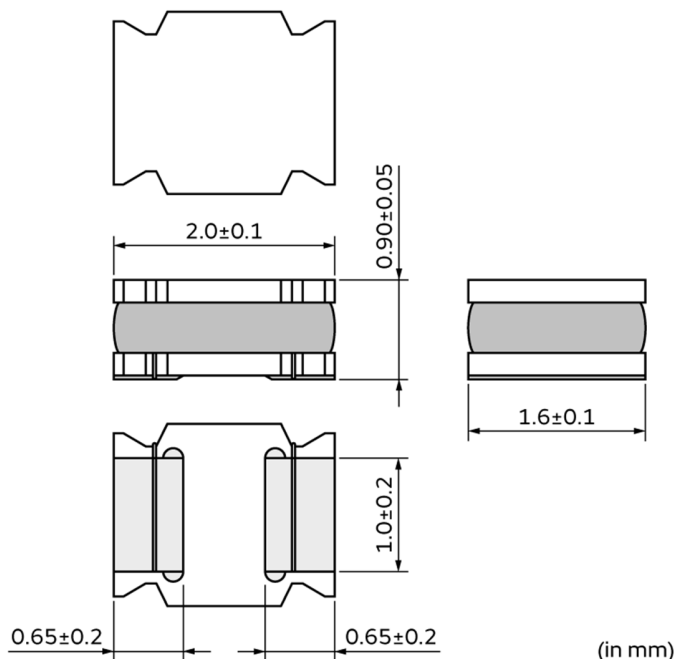
When rated current is applied to the products, temperature rise caused by self-generated heat shall be limited to 20°C max (ambient temperature 85°C to 105°C).

\*3 Keep the temperature (ambient temperature plus self-generation of heat) under 125°C.

**4. Testing Conditions**

Unless otherwise specified	Temperature: ordinary temperature (15°C to 35°C) Humidity: ordinary humidity [25% to 85% (RH)]
In case of doubt	Temperature: 20°C±2°C Humidity: 60% to 70% (RH) Atmospheric pressure: 86 kPa to 106 kPa

**5. Appearance and Dimensions**



Unit mass (typical value): 0.010 g

**6. Marking**

No marking.

**7. Electrical Performance**

No.	Item	Specification	Test method
7.1	Inductance	Meet chapter 3 ratings.	Measuring equipment: Keysight 4192A or the equivalent Measuring frequency: 1 MHz
7.2	DC resistance	Meet chapter 3 ratings.	Measuring equipment: digital multimeter
7.3	Self-resonant frequency	Meet chapter 3 ratings.	Measuring equipment: Keysight E4991A or the equivalent

**8. AEC-Q200 Requirement**

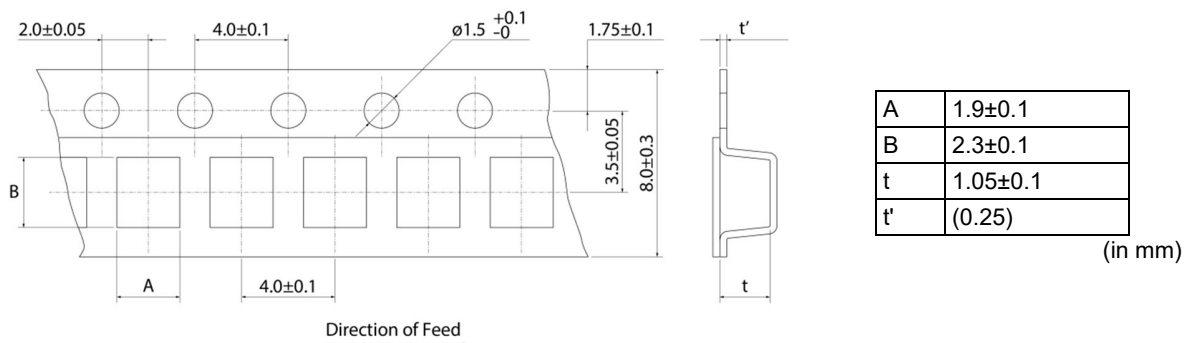
**8.1 Performance [based on table 5 for magnetics (inductors/transformer) AEC-Q200 Rev. D issued June 1, 2010]**

AEC-Q200			Murata specification/deviation	
No.	Stress	Test method		
3	High temperature exposure	1000 h at 125°C Set for 24 h at room condition, then measured.	Meet table A after testing. Table A	
			Appearance	No damage
			Inductance change (at 1 MHz)	Within ±10%
			DC resistance change	Within ±10%
4	Temperature cycling	1000 cycles -40°C to +105°C Set for 24 h at room condition, then measured.	Meet table A after testing.	
7	Biased humidity	1000 h at 85°C, 85% (RH). Unpowered.	Meet table A after testing.	
8	Operational life	Apply 85°C 1000 h Set for 24 h at room condition, then measured.	Meet table A after testing.	
9	External visual	Visual inspection	No abnormalities	

AEC-Q200			Murata specification/deviation						
No.	Stress	Test method							
10	Physical dimension	Meet chapter 5, "Appearance and Dimensions".	No defects						
12	Resistance to solvents	Per MIL-STD-202 Method 215	Not applicable						
13	Mechanical shock	Per MIL-STD-202 Method 213 Condition C: 100 g's/6 ms/half sine	Meet table A after testing.						
14	Vibration	5 g's for 20 min, 12 cycles each of 3 orientations Test from 10 Hz to 2000 Hz	Meet table A after testing.						
15	Resistance to soldering heat	No-heating Solder temperature 260°C±5°C Immersion time 10 s	Pre-heating: 150°C to 180°C/90 s±30 s Meet table B after testing. Table B <table border="1" style="margin-left: 20px;"> <tr> <td>Appearance</td> <td>No damage</td> </tr> <tr> <td>Inductance change (at 1 MHz)</td> <td>Within ±20%</td> </tr> <tr> <td>DC resistance change</td> <td>Within ±10%</td> </tr> </table>	Appearance	No damage	Inductance change (at 1 MHz)	Within ±20%	DC resistance change	Within ±10%
Appearance	No damage								
Inductance change (at 1 MHz)	Within ±20%								
DC resistance change	Within ±10%								
17	ESD	Per AEC-Q200-002	Meet chapter 3 ratings. No defects						
18	Solderability	Per J-STD-002	Method b: not applicable 90% of the terminations is to be soldered (except exposed wire).						
19	Electrical characterization	Measured: inductance	No defects						
20	Flammability	Per UL-94	Not applicable						
21	Board flex	Epoxy-PCB (1.6 mm) Deflection 2 mm (min.) 60 s minimum holding time	Murata deviation request: 5 s Meet table A after testing.						
22	Terminal strength	Per AEC-Q200-006 A force of 17.7 N for 60 s	Murata deviation request: 5 N for 60 s No defects						

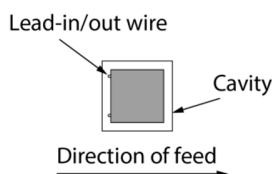
## 9. Specification of Packaging

### 9.1 Appearance and dimensions of tape (8 mm width/plastic tape)



\* The dimensions of the cavity are measured at its bottom.

■ Top view



## 9.2 Taping specifications

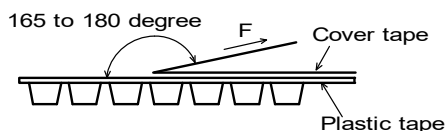
Packing quantity (Standard quantity)	3000 pcs/reel
Packing method	The products are placed in embossed cavities of a plastic tape and sealed by a cover tape.
Feed hole position	The feed holes on the plastic tape are on the right side when the cover tape is pulled toward the user.
Joint	The plastic tape and the cover tape are seamless.
Number of missing products	Number of missing products within 0.025% of the number per reel or 1 pc., whichever is greater, and are not continuous. The specified quantity per reel is kept.

## 9.3 Break down force of tape

Break down force of plastic tape	10 N min.
Break down force of cover tape	10 N min.

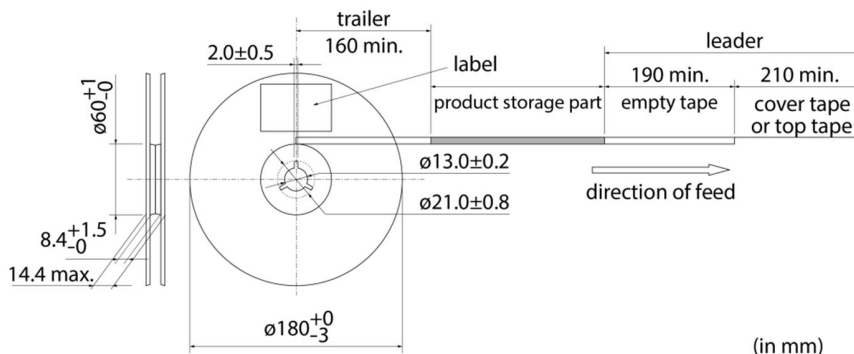
## 9.4 Peeling off force of cover tape

Speed of peeling off	300 mm/min
Peeling off force	0.2 N to 0.7 N (The lower limit is for typical value.)



## 9.5 Dimensions of leader section, trailer section and reel

A vacant section is provided in the leader (start) section and trailer (end) section of the tape for the product. The leader section is further provided with an area consisting only of the cover tape (or top tape). (See the diagram below.)



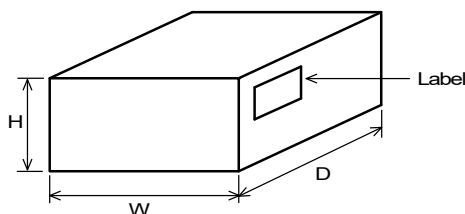
## 9.6 Marking for reel

Customer part number, Murata part number, inspection number (\*1), RoHS marking (\*2), quantity, etc.

*1 Expression of inspection No.: $\frac{\square\square}{(1)}$ $\frac{\circ\circ\circ\circ}{(2)}$ $\frac{\diamond\diamond\diamond}{(3)}$	(1) Factory code (2) Date First digit: year/last digit of year Second digit: month/Jan. to Sep.→1 to 9, Oct. to Dec.→O, N, D Third, Fourth digit: day (3) Serial No.
*2 Expression of RoHS marking: ROHS- $\frac{Y}{(1)}$ $\frac{(\Delta)}{(2)}$	(1) RoHS regulation conformity (2) Murata classification number

## 9.7 Marking on outer box (corrugated box)

Customer name, purchasing order number, customer part number, Murata part number, RoHS marking (\*2), quantity, etc.

**9.8 Specification of outer box**

Dimensions of outer box (mm)			Standard reel quantity in outer box (reel)
W	D	H	
186	186	93	5
* Above outer box size is typical. It depends on a quantity of an order.			

**10. ⚠Caution****10.1 Restricted applications**

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects which might directly cause damage to the third party's life, body or property.

- |                                   |   |
|-----------------------------------|---|
| (1) Aircraft equipment            | (6) Disaster/crime prevention equipment   |
| (2) Aerospace equipment           | (7) Traffic signal equipment  |
| (3) Undersea equipment            | (8) Transportation equipment (trains, ships, etc.)  |
| (4) Power plant control equipment | (9) Data-processing equipment   |
| (5) Medical equipment             | (10) Applications of similar complexity and/or reliability requirements to the applications listed in the above |

**10.2 Precautions on rating**

Do not use the products in excess of their rated current. Doing so may cause the product to generate heat, resulting in short circuit between wires, wire breakage, or melted solder, which may cause dropping of parts.

**10.3 Fail-safe**

Be sure to provide an appropriate fail-safe function on your product to prevent a second damage that may be caused by the abnormal function or the failure of our product.

**10.4 Corrosive gas**

Please refrain from use since contact with environments with corrosive gases (sulfur gas [hydrogen sulfide, sulfur dioxide, etc.], chlorine, ammonia, etc.) or oils (cutting oil, silicone oil, etc.) that have come into contact with the previously stated corrosive gas environment will result in deterioration of product quality or an open from deterioration due to corrosion of product electrode, etc. We will not bear any responsibility for use under these environments.

**11. Precautions for Use**

This product is for use only with reflow soldering. It is designed to be mounted by soldering. If you want to use other mounting method, for example, using a conductive adhesive, please consult us beforehand.

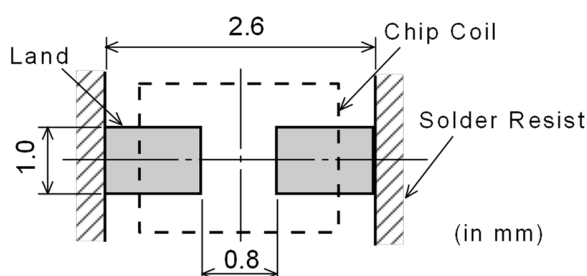
Also, if repeatedly subjected to temperature cycles or other thermal stress, due to the difference in the coefficient of thermal expansion with the mounting substrate, the solder (solder fillet part) in the mounting part may crack.

The occurrence of cracks due to thermal stress is affected by the size of the land where mounted, the solder volume, and the heat dissipation of the mounting substrate. Carefully design it when a large change in ambient temperature is assumed.

**11.1 Land dimensions**

The following diagram shows the recommended land dimensions for reflow soldering.

The land dimensions are designed in consideration of electrical characteristics and mountability. Use of other land dimensions may preclude achievement of performance. In some cases, it may result in poor solderability, including positional shift. If you use other land pattern, consider it adequately.



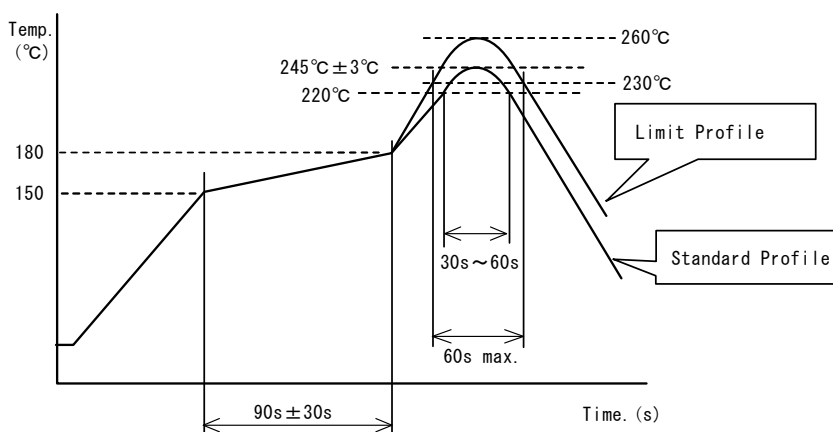
**11.2 Flux and solder used**

Flux	<ul style="list-style-type: none"> <li>• Use a rosin-based flux.</li> <li>• Do not use a highly acidic flux with a halide content exceeding 0.2(wt)% (chlorine conversion value).</li> <li>• Do not use a water-soluble flux.</li> </ul>
Solder	<ul style="list-style-type: none"> <li>• Use Sn-3.0Ag-0.5Cu solder.</li> <li>• Standard thickness of solder paste: 100 μm to 150 μm</li> </ul>

If you want to use a flux other than the above, please consult our technical department.

**11.3 Soldering conditions (reflow)**

- Pre-heating should be in such a way that the temperature difference between solder and product surface is limited to 100°C max.  
Cooling into solvent after soldering also should be in such a way that the temperature difference is limited to 100°C max. Insufficient pre-heating may cause cracks on the product, resulting in the deterioration of product quality.
- Standard soldering profile and the limit soldering profile is as follows.  
The excessive limit soldering conditions may cause leaching of the electrode and/or resulting in the deterioration of product quality.



	Standard profile	Limit profile
Pre-heating	150°C to 180°C/90 s ± 30 s	150°C to 180°C/90 s ± 30 s
Heating	Above 220°C/30 s to 60 s	Above 230°C/60 s max.
Peak temperature	245°C ± 3°C	260°C/10 s
Number of reflow cycles	2 times	2 times

**11.4 Reworking with soldering iron**

The following requirements must be met to rework a soldered product using a soldering iron.

Item	Requirement
Pre-heating	150°C/approx. 1 min
Tip temperature of soldering iron	350°C max.
Power consumption of soldering iron	80 W max.
Tip diameter of soldering iron	ø3 mm max.
Soldering time	3 s (+1 s, -0 s)
Number of reworking operations	1 time max.
* Avoid a direct contact of the tip of the soldering iron with the product. Such a direction contact may cause cracks in the ceramic body due to thermal shock.	

**11.5 Solder volume**

Solder shall be used not to increase the volume too much.

An increased solder volume increases mechanical stress on the product. Exceeding solder volume may cause the failure of mechanical or electrical performance.

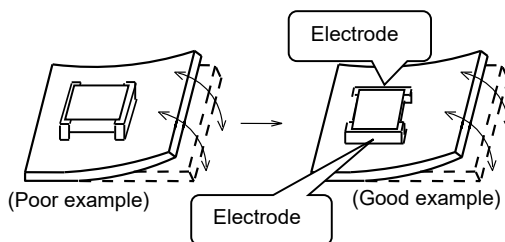
**11.6 Product's location**

The following shall be considered when designing and laying out PCBs.

- (1) PCB shall be designed so that products are not subject to mechanical stress due to warping the board.

[Products direction]

Products shall be located in the sideways direction to the mechanical stress.

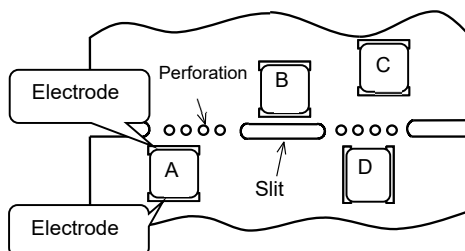


**(2) Components location on PCB separation**

It is effective to implement the following measures, to reduce stress in separating the board.

It is best to implement all of the following three measures; however, implement as many measures as possible to reduce stress.

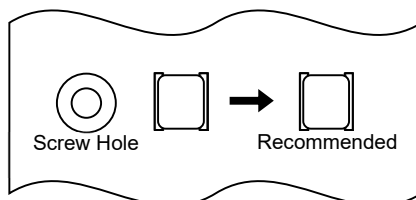
Contents of measures	Stress level
(1) Turn the mounting direction of the component parallel to the board separation surface.	$A > D^{*1}$
(2) Add slits in the board separation part.	$A > B$
(3) Keep the mounting position of the component away from the board separation surface.	$A > C$
*1 $A > D$ is valid when stress is added vertically to the perforation as with hand separation. If a cutting disc is used, stress will be diagonal to the PCB, therefore $A > D$ is invalid.	



**(3) Mounting components near screw holes**

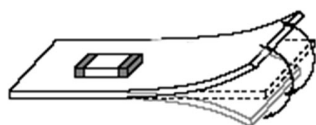
When a component is mounted near a screw hole, it may be affected by the board deflection that occurs during the tightening of the screw.

Mount the component in a position as far away from the screw holes as possible.

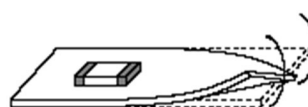


**11.7 Handling of substrate**

After mounting products on a substrate, do not apply any stress to the product caused by bending or twisting to the substrate when cropping the substrate, inserting and removing a connector from the substrate or tightening screw to the substrate. Excessive mechanical stress may cause cracking in the product.



Bending



Twisting

**11.8 Cleaning**

The product shall be cleaned under the following conditions.

- (1) The cleaning temperature shall be 60°C max. If isopropyl alcohol (IPA) is used, the cleaning temperature shall be 40°C max.
- (2) Perform ultrasonic cleaning under the following conditions. Exercise caution to prevent resonance phenomenon in mounted products and the PCB.

Item	Requirement
Power	20 W/L max.
Time	5 min max.
Frequency	28 kHz to 40 kHz

- (3) Cleaner  
 Alcohol-based cleaner: IPA  
 Aqueous agent: PINE ALPHA ST-100S
  - (4) There shall be no residual flux or residual cleaner. When using aqueous agent, rinse the product with deionized water adequately and completely dry it so that no cleaner is left.
- \* For other cleaning, consult our technical department.

**11.9 Storage and transportation**

Storage period	Use the product within 12 months after delivery. If you do not use the product for more than 12 months, check solderability before using it.
Storage conditions	<ul style="list-style-type: none"> <li>• The products shall be stored in a room not subject to rapid changes in temperature and humidity. The recommended temperature range is -10°C to +40°C. The recommended relative humidity range is 15% to 85%. Keeping the product in corrosive gases, such as sulfur, chlorine gas or acid, oxidizes the electrode, resulting in poor solderability or corrosion of the coil wire of the product.</li> <li>• Do not keep products in bulk packaging. Doing so may cause collision between the products or between the products and other products, resulting in core chipping or wire breakage.</li> <li>• Do not place the products directly on the floor; they should be placed on a palette so that they are not affected by humidity or dust.</li> <li>• Avoid keeping the products in a place exposed to direct sunlight, heat or vibration.</li> </ul>
Transportation	Excessive vibration and impact reduces the reliability of the products. Exercise caution when handling the products.

**11.10 Resin coating**

The inductance value may change due to high cure-stress of resin to be used for coating/molding products.

A wire breakage issue may occur by mechanical stress caused by the resin, amount/cured shape of resin, or operating condition etc. Some resin contains some impurities or chloride possible to generate chlorine by hydrolysis under some operating condition may cause corrosion of wire of coil, leading to wire breakage.

So, please pay your careful attention when you select resin in case of coating/molding the products with the resin.

Prior to use the coating resin, please make sure no reliability issue is observed by evaluating products mounted on your board.

**11.11 Handling of product**

- Sharp material such as a pair of tweezers or other material such as bristles of cleaning brush, shall not be touched to the winding portion to prevent the breaking of wire.
- Mechanical shock should not be applied to the products mounted on the board to prevent the breaking of the core.

**11.12 Heat-resistant temperature of substrate and peripheral components**

A rated current applied to the product (based on a rise in temperature) increases the product temperature up to 40°C. Pay attention to the heat-resistant temperature of the substrate and peripheral components.

**12.  Note**

- (1) Please make sure that your product has been evaluated in view of your specifications with our product being mounted to your product.
- (2) You are requested not to use our product deviating from the reference specifications.
- (3) The contents of this reference specification are subject to change without advance notice. Please approve our product specifications or transact the approval sheet for product specifications before ordering.

## Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

- ⊖ [View LQH2MPZ2R2MGRL on WIN SOURCE](#)
- ⊖ [Murata Electronics North America Information](#)

## Optimize Your Supply Chain with WIN SOURCE Solutions

- ✓ Global Sourcing Solution
- ✓ Obsolete Management
- ✓ Cost Control Management
- ✓ Shortage Management
- ✓ Alternative Solution
- ✓ Excess Inventory Management